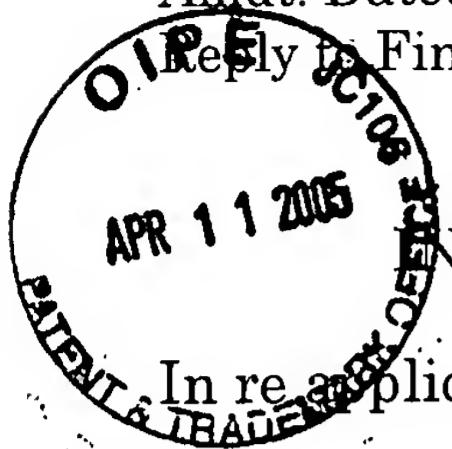


Appl. No. 10/622,038  
Amdt. Dated April 7, 2005  
Reply to Final Office Action of January 7, 2005

Attorney Docket No. 81754.0096  
Customer No. 26021



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Takashi TAKAMURA

Serial No. 10/622,038

Confirmation No. 2258

Filed: July 17, 2003

For: Method for Preventing Electrostatic  
Damage to a Semiconductor Chip  
Package During Storage (as amended)

Art Unit: 2814

Examiner: Dilinh P. Nguyen

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Name

 04/07/05

Signature

Date

**AMENDMENT**

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the final Office Action dated January 7, 2005, please amend  
this application as follows:

**Amendments to the Claims** are reflected in the listing of claims, which  
begins on page 2 of this paper.

**Remarks/Arguments** begin on page 4 of this paper.